MYON MicroModule SOM



SOM-Myon-I-410E

Micro CPU module with Snapdragon™ 410E

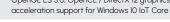
Thanks to the compact form factor ideal for IoT and battery-powered handheld devices



HIGHLIGHTS







()) Available in Industrial Temperature Range

OUALCOMM

Transportation



(10750)

Industrial

Automation

Smart Devices



Smart Buldings & Digital Signage

Smart Cities

CONNECTIVITY

MEMORY

Onboard WLAN 802.11 b/g/n 2.4 GHz, BT 4.1, USB 2.0, LVDS, MIPI Display and Camera

EMCP incl. LPDDR3 -1066 (533MHz) up to 2

GByte and eMMC up to 16 Gbyte

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Energy & Utilities

FEATURES

MAIN FIELDS OF APPLICATION

Coffee &

Vending

Processor	Qualcomm [®] Snapdragon [™] 410E QuadCore ARM Cortex A53, up to 1.2GHz (APQ8016E), ARM Cortex M3
A Memory	1 GByte LPDDR3 -1066 (533MHz), 32Bit, 2 Gbyte on request (part of EMCP)
Graphics	Qualcomm® Adreno™ 306 400MHz GPU OpenGL ES 3.0, OpenCL, DirectX
Video Interfaces	LVDS or MIPI Display (4 channel)
Video Resolution	LVDS, MIPI: 1080p @30
Mass Storage	8 Gbyte eMMC, 16 Gbyte on request (part of EMCP)
5 ^모 과 Networking	Onboard WLAN 802.11 b/g/n 2.4 GHz, BT 4.1 (Onboard antennas or UFL connectors) Ethernet via USB possible
⊷ USB	USB 2.0 OTG
III Audio	Audio Codec: Stereo Headphone output, Mono Speaker $8\Omega, \ 3$ Microphone inputs

Medical

W	Other Interfaces	SD/SDIO Card, MIPI Camera (2ch and 4Ch) 8 Ports configurable for different interfaces: GPIO, UART, SPI, I2C, I2S
	Power Supply	LiPo 3 - 4.5V / typ. 3.3V / charger 5V
os	Operating System	Windows 10 IoT Core Linux Android
	Operating Temperature*	-25 ÷ 85°C
L	Dimensions	48 x 32 x 4.2 mm

*All carrier board components must remain within the operating temperature at any and all times, including start-up; carrier operating temperature is independent of the module installed. Please refer to the specific module for more details. Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.



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BLOCK DIAGRAM

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	_			- -		
Module-Connect	or #1		Qualcomm SnapDragon 410E		eMCP eMMC	
UART,SPI or I2C	Port 1		Arm Quad Cortex A53 1.2 GHz		8 GByte	
UART,SPI or I2C	Port 2		512kB L2 Cache		LPDDR3 32-bit	
SPI or I2C	Port 3		Arm Cortex-M3		1 GByte	
SPI or I2C	Port 4				WLAN + Bluetooth	
GPIO,PWM,	All Ports				802.11 a/b Bluetooth 4	
USB2.0			Qualcomm Adreno 306 GPU OpenGL ES 3.0 OpenCL, DirectX			
SDIO	J		Decoder: 1080p30 H.264, Encoder: 1080p30 H.264			
			1080p30 Display x1			
		l				
					Madula C	onnector #2
LVDS	MIPI->L	VDS	JTAG SnapDragon			
4ch Mipi DSI	Mipi D I2C	SI			Port 5	SPI or I2C
	Audio Cod	loc			Port 6	SPI or I2C
Headphone					Port 7	125
					Port 8	125
Microphone ×3]				All Ports	GPIO,PWM,
Speaker	J					[
4,36V VIN	РМІС					4ch Mipi CSI
34,5V VBAT	with battery-cha					2ch Mipi CSI
+3V3 Out						
+1V8 Out						
VDD_IO Out	I2C Power	· Sup.				



Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

DATA ORCHESTRATION

Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI. PORTAL Analyze data from rer

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



